



**SYPRIS ELECTRONICS
PURCHASE ORDER ATTACHMENT "Q"**

Rev. MARCH 23, 2010

* NOTE: CONTACT MIKE BRANDON AT (813) 972-6175 TO VERIFY IF DOCUMENT IS MOST RECENT

(The coded Requirements listed within this Attachment are applicable to material furnished under the Purchase Order upon which they are referenced. If a code referenced on the Purchase Order cannot be located within this document, notify the appropriate Sypris Electronics Purchasing agent for clarification prior to shipment of product. Failure to comply with these requirements, when referenced on the Purchase Order, will be cause for rejection of material at Sypris Electronics Receiving Inspection. In the event of conflict between the requirements listed herein and Purchase Order text, the Purchase Order shall prevail.)

- A01** **INSPECTION SYSTEM** - The Subcontractor/ Supplier shall maintain an inspection system which will assure that all supplies and services delivered to Sypris Electronics conform to the applicable requirements, whether manufactured or processed by the Supplier, or procured from a lower tier supplier. The Supplier shall perform or have performed the inspections and tests required to substantiate product conformance to drawing, specifications and contract requirements and shall also perform or have performed all inspections and tests otherwise required by the P.O. The Supplier's inspection system shall be documented and shall be available for review. Supplier will notify Sypris Electronics and obtain prior approval before making any changes in product and/or process definitions, which affect form, fit or function. This includes any deviations to specified approved material suppliers and/or substitutions to component part numbers. Supplier will notify Sypris Electronics and obtain prior approval before shipping nonconforming product.
- A02** **J-STD-001 Class 3** – This assembly shall be manufactured in accordance with IPC/EIA J-STD-001 Class 3 and shall meet the inspection criteria as specified in IPC-A-610 Class 3.
- A03** **QUALITY SYSTEM** - The subcontractor/ supplier shall maintain a quality system in accordance with ISO 9001:2000 or Sypris Electronics approved equivalent. Supplier will notify Sypris Electronics and obtain prior approval before making any changes in product and/or process definitions, which affect form, fit or function. This includes any deviations to specified approved material suppliers and/or substitutions to component part numbers. Supplier will notify Sypris Electronics and obtain prior approval before shipping nonconforming product.
- A04** **QUALITY SYSTEM** - The subcontractor/ supplier shall maintain a quality system in accordance with AS9100 or Sypris Electronics approved equivalent. Supplier will notify Sypris Electronics and obtain prior approval before making any changes in product and/or process definitions, which affect form, fit or function. This includes any deviations to specified approved material suppliers and/or substitutions to component part numbers. Supplier will notify Sypris Electronics and obtain prior approval before shipping nonconforming product.
- A20** **OFFSHORE APPROVAL** - No subcontracts or purchase orders which involve design, manufacture, production, assembly or test in a location not in the United States, of equipment, assemblies, accessories or parts which are not covered by a Specification or a Standard listed in MIL-P-11268, MIL-E-16400 or MIL-E-5400 shall be made under this contract without specific approval of the contracting officer.
- A21** **OFFSHORE APPROVAL** - No subcontracts or purchase orders which involve design, manufacture, production, assembly or test in a location not in the United States, of equipment, assemblies, accessories or parts which are not covered by a Specification or a Standard listed in MIL-P-11268, MIL-E-16400 or MIL-E-5400 shall be made under this contract without specific approval of the contracting officer. Parts, excluding Large Scale Integrated Circuits (LSIC) or any likeness thereof, may be procured from

distributors located in the United States even if this distributor is supplied from a manufacturer not located in the United States as long as the distributor complies with the requirements of Quality Code G24 herein.

- C03** **RIGHT OF ENTRY** - Sypris Electronics, its customers and regulatory agencies reserve the right of entry, within a mutually agreed time, to any place necessary to determine and verify the quality of contracted work, records and material.
- C06** **Certificate of Conformance** - The manufacture shall provide a signed hard copy Certificate of Conformance with each shipment stating that the articles provided per this order have been manufactured, tested, and inspected in accordance with all requirements set forth by this purchase order.
- CFM** This material is Customer Furnished and the customer agrees to provide the material in a production ready condition. Production ready is defined as follows:
- Material properly identified, packaged, and shipped in a manner to prevent electrical, mechanical, and/or ESD damage.
 - Leads prepped/formed in accordance with specification as applicable.
 - Lead finish in accordance with applicable J-STD requirements.
 - SMT material properly taped and reeled and/or trayed in accordance with JEDEC standards.
 - Moisture sensitive material identified and packaged in accordance with J-STD-033A.
 - Material shall be capable of meeting all specified contract solderability requirements.

NOTE: A separate Sypris Receiving Inspection Instruction will not be issued, see below for inspection criteria.

Using this instruction within this Q-Code, Incoming Inspection will be performed on all CFM material as follows:

1. Verify material was not mechanically damaged during shipment.
2. Verify that the part number as it appears on the label affixed to the packaging matches the part number on the PO.
3. Any SMT components are properly taped and reeled or in appropriate JEDEC trays.
4. Material identified as moisture sensitive is appropriately packaged.

CPU TECH flow downs:

- C1** **Workmanship** – The Supplier shall meet the requirements as specified in CPU Tech Workmanship Standard 040-100100-001 Rev 1 (draft). Please contact Sypris purchasing department to obtain a copy.
- C2** **Pull Test Data** - Supplier shall maintain evidence of pull tests and data used to verify crimps and proof of load values. This data shall be maintained for 7 years after last shipment and made available to Sypris prior to destroying.
- C3** **1st Piece Inspection** – Supplier shall provided a one piece sample of each part number for inspection and approval by Sypris prior to beginning full production.
- E50** **SOLDERABILITY** - Parts shall be capable of meeting the solderability requirements of Category 3 durability as defined in ANSI/J-STD-002 or equivalent. Surface mount devices shall be pretinned using SnPb 63/37 or 60/40 with no copper, gold, or base metal visible on the solderable surface. NOTE: This requirement is not applicable to parts governed by military specifications or standards.
- BGA's that are RoHS compliant or otherwise have lead free solder balls MUST NOT be substituted for the part # ordered. NOTE: All BGA's MUST contain tin/lead (Sn:63/Pb:37) solder balls as originally provided by the OEM.
- F05** **ESD Q-CODE** - All ESD sensitive components shall be handled, packaged, marked, and shipped to Sypris Electronics' in accordance with the requirements specified in ANSI/ESD-S20.20.

- G10** **MARKING** – Packing slips and lowest level of packaging shall be marked as a minimum with the following:
- 1) Manufacturer
 - 2) Manufacturer Part Number
 - 3) Customer Part Number
 - 4) Quantity
- G24** **MARKING** - Subcontracts, purchase orders, drawings, travelers and other related type documents provided to offshore vendors will not carry any 0NXXXXXX/98230 identification, nor will they reveal the Government prime contract number. No reference to DOD or MPO shall be made on the offshore procurement. Offshore manufactured parts are not to be identified with the "0N" part number designation until after they are received in the United States. If Government Source Inspection has been imposed on this order, Government verification will be required. If parts marked with the MPO identification code (0NXXXXXX/98230), including rejects, are allocated for non-MPO programs or for resale to other customers, then the markings associated with the MPO identification code must be removed from the parts before the parts are sent to non-MPO programs or other customers.
- J06** **DATA, TEST DATA** - Suppliers are required to include a copy of the Quality Conformance Inspection Data (attributes data is acceptable) with each shipment covering the parts shipped. Any calculations, assumptions or failure analysis used to substantiate test results must be detailed.
- J07** **FIRST PIECE INSPECTION DATA** – A supplier furnishing material manufactured to an assembly drawing will include a First Piece Inspection Data Report with the first shipment to Sypris Electronics. At a minimum, the First Piece Inspection will be a 100% dimensional inspection.
- J08** **AS 9102 - FIRST ARTICLE INSPECTION REPORT (FAIR)** – A supplier furnishing material manufactured in accordance with this P.O. for the first time, or after a 2 year laps of production, or in the case of a revision change (only data on the delta) shall provide a First Article Inspection Report with the first shipment of material shipped to Sypris Electronics. The First Article Inspection Data shall be in accordance with the requirements of SAE AS 9102. Data on forms other than those listed in AS9102 **shall not be used** and will not be accepted. The acceptable AS9102 forms can be obtained at <http://www.sae.org/aagg/publications/as9102af1.doc>, /as9102af2.doc, and /as9102af3.doc.
- Attribute data (go/no-go) may be used if no inspection technique resulting in variable data is feasible. Attribute data is permitted when the design characteristic does not specify numerical limits (e.g. break all sharp edges). It is also permitted where qualified tooling is consistently used as a check feature and a go/no-go feature has been established for the specific characteristic. "ACCEPT" or "REJECT" shall be entered as a result of this inspection, as applicable.
- Copies of all test records, certifications (Certifications of Conformance/Compliance must be specifically annotated with the product, raw materials, shelf-life materials, processes, special processes, finishes, marking inks, etc... call outs exactly as they appear on the drawing and must include lot code/batch/heat numbers, expiration dates. Etc), and other substantiating quality data is attached to the forms for applicable detail/subassembly or assembly and is considered an integral part of the submitted FAI report.
- K01** **AXIAL LEADED COMPONENTS** – Parts shall be taped in accordance with EIA Standard EIA-296-E with the following exceptions:
1. For parts 0.200 inch long or less, the "B" dimension shall be 2.062 ±0.062. The "A" dimension shall be 0.200 (+0.200, -0.020) with maximum lead length sufficient to extend through width of tape.
 2. Lead trim is preferred to be flush with outside edge of tape. However, maximum extension may be 0.50 inch if trim is even.
 3. For RCR05 resistors, the "B" dimension shall be 2.00 to 2.10 inches.
- K02** **RADIAL LEADED COMPONENTS** - Parts shall be taped in accordance with EIA Standard EIA-468-B with the following exception:
- Dimension "H" shall be 17mm minimum.

K03 **ALL COMPONENTS** - Parts shall be packaged to prevent bending or damage to leads, seals, bodies, and lowest level packaging. In addition batteries, which could electrically short when coming in contact with one another shall be individually packaged or wrapped at the lowest level of packaging to prevent electrical shorts.

K05 **DUAL-IN-LINE PACKAGE** – Parts shall be supplied in sticks suitable for use with automatic handling equipment.

K20 Moisture sensitive part packaging requirements – **See Q-Code K30 or K32**

K30 (-cc-nnn-vv-xx)

SURFACE MOUNT & PIN GRID ARRAY DEVICES - TRAYS - Surface mount and Pin Grid Array (PGA) devices shall be supplied in JEDEC style anti-static trays capable of withstanding 130°C. The JEDEC style trays shall be in accordance with JEDEC Publication JEP95.

Components that are classified as being sensitive to moisture absorption shall be supplied in accordance with IPC/JEDEC J-STD-033A.

OPTIONAL CHARACTERS: -cc-nnn-vv may be specified to define the JEDEC tray.

The JEDEC drawing type, tray variation, and component orientation are in the format cc-nnn-vv-xx.

For example, K30-CS-004-AA-TL requires the part to be packaged in a tray conforming to JEDEC Carrier Standard 004, Variation AA, Component Pin 1 orientation is to Top Left corner of tray towards tray chamfer.

-xx component tray orientation shall be determined per Plan View of tray in JEDEC STD 95-1. Per Plan View, tray chamfer is located in Top Left corner of tray. Characters utilized to indicate orientation for Top and Left. shall be T and L. Two digit characters used shall be TL, TC, and TR for Top/Left, Top/Center, and Top/Right; LT, LC, and LB for Left/Top, Left/Center, and Left/Bottom.

Other rigid trays may also be acceptable. If a non-JEDEC defined tray is acceptable, the tray manufacturer's designation shall be specified in place of the optional JEDEC tray identifier.

K32(-ww-pp)

SURFACE MOUNT DEVICES – TAPE AND REEL – Surface mount devices shall be supplied on anti-static embossed tape or punched tape in accordance with EIA Standard EIA-481 and EIA Guideline EIA-783. Loose or bulk devices will not be accepted.

Components that are classified as being sensitive to moisture absorption shall be supplied in accordance with IPC/JEDEC J-STD-033A.

OPTIONAL CHARACTERS: -ww-pp may be specified to define the tape width and cavity pitch on the tape.

-ww is the tape width in millimeters. Allowed values are: 08, 12, 16, 24, 32, 44 or 56.

-pp is the cavity pitch in millimeters on the tape.

Pitch may only be specified if the tape width is also specified.

Allowed values are: 02, 04, 08, 12, 16, 20, 24, 28, 32, 36, 40, 44, 48, 52 or 56.

L01 **SAFETY** - The material must be accompanied by a copy of Material Safety Data Sheet as specified in 29 C.F.R. 1910.1200, or an exemption to this standard signed by a representative of your company.

PTM **PROTOTYPE MATERIAL**

SURFACE MOUNT & PIN GRID ARRAY DEVICES - TRAYS - Surface mount and Pin Grid Array (PGA) devices shall be supplied in JEDEC style anti-static trays capable of withstanding 130°C. The JEDEC style trays shall be in accordance with JEDEC Publication JEP95.

SURFACE MOUNT DEVICES – TAPE AND REEL – Surface mount devices shall be supplied on anti-static embossed tape or punched tape in accordance with EIA Standard EIA-481 and EIA Guideline EIA-783. Loose or bulk devices will not be accepted.

ALL COMPONENTS - Parts shall be packaged to prevent bending or damage to leads, seals, bodies, and lowest level packaging. In addition batteries, which could electrically short when coming in contact with one another shall be individually packaged or wrapped at the lowest level of packaging to prevent electrical shorts.

Components which are classified as being sensitive to moisture absorption shall be supplied in accordance with IPC/JEDEC J-STD-033A.

ESD - All ESD sensitive components shall be handled, packaged, marked, and shipped to Sypris Electronics' in accordance with the requirements specified in ANSI/ESD-S20.20.

T01 **WIRE** – Wire and/or cable shall be supplied in one continuous length per spool. Splices are allowed providing the joint does not exceed the overall diameter of the wire or cable. Minimum lengths of 100 feet are required between splices. All spools will be identified as to lengths on them.

U10 **PRINTED CIRCUIT BOARDS / COUPONS REQUIRED** - Printed Circuit Boards shall meet the requirements of the applicable specification as noted on the drawing. Results of micro-section analysis or Group A test data per applicable specification shall accompany each shipment of boards. Electrical test data, C of C, and inspection data shall be included with each shipment. Quality conformance test coupons from the panels corresponding to the boards produced from them shall accompany the boards shipped. These coupons shall be traceable to the boards produced from the panels. A sample of these coupons shall be selected randomly per the applicable requirement(s); they shall be cross-sectioned accordingly and shall accompany the boards and coupon strips shipped. The cross-sections MUST represent the X and Y directions for annular ring purposes. First article dimensional data shall be included with the first shipment of each new PCB or Rev. change. A solder-ability sample for each date/lot code shall be included with each shipment. Any deviations shall require advance Sypris Electronics approval.

PCB HUMIDITY CONTROL PACKAGING –

PCB must be packaged in Nylon/Foil/Poly or equivalent – A commonly available Moisture Barrier Bag (MBB) construction incorporating an outer layer of static dissipative nylon, an aluminum foil middle layer, and an inner layer of polyethylene. This structure provides very good moisture barrier characteristics with typical WVTR values of < 0.0005 gm/100 in2). **Desiccant** The quantity and quality of the desiccant material selected should be in accordance with IPC-J-STD-033. **Humidity Indicator Card (HIC)** The type and usage of the HIC should be in accordance with IPC-J-STD-033. **Packaging Methods - Internal (Dry Packaging)** Prior to packaging, the PBs should be clean and dry. **Recommended Moisture Levels Prior to Packaging** When using high temperature processing (maximum 260 °C) (such as lead-free), the moisture levels prior to packaging should not exceed 0.1%. When using low temperature processing (maximum 230 °C), the moisture levels prior to packaging should not exceed 0.2%.

U11 **PRINTED CIRCUIT BOARDS with unfilled via hole-in-pad technology:**

1. Photos of micro-sections of via hole-in-pad must be provided by the PWB manufacturer for each manufacturing lot and shall be submitted to Sypris Electronics with each shipment.
2. Copper overhang is not allowed in blind via hole-in-pad.
3. Via hole-in-pad must exhibit all the plating elements specified by the drawing.
4. The conductive surface of the via in-hole pads must be free of contaminants that affect solderability, life, ability to assemble and serviceability.

U12 **PRINTED CIRCUIT BOARDS with filled via hole-in-pad technology:**

1. Photos of micro-sections of via hole-in-pad must be provided by the PWB manufacturer for each manufacturing lot and shall be submitted to Sypris Electronics with each shipment.
2. Add to all 0.006" micro via holes to be filled with copper and plate with gold. The allowable via fill depression is not to exceed 0.003". The allowable via cap plating shall have no voids, 0.0015" max

separations and no more than 25% of the diameter of the pad. The via cap plating shall be at a minimum of 0.0003".

- U15** **PRINTED CIRCUIT BOARDS / NO COUPONS REQUIRED** – Printed Circuit Boards shall meet all drawing requirements. Suppliers shall send written results of microsection inspection, a sample thermal stressed microsection for each date/lot code shipped, and a C of C. Minimum plated copper in holes shall be .001" unless otherwise noted on drawing or specification. PCB's shall meet the solderability requirements per ANSI/J-STD-003 Class 2. A solderability sample for each date/lot code shall be included with each shipment. First article dimensional data shall be included with the first shipment of each new PCB or Rev. change. Any deviations shall require advance Sypris Electronics approval.
- U16** PWB's shall not be manufactured using HASL, (Hot air Solder Leveling) and its relative cleaning process. PWB's shall be manufactured using tin/lead plating processes and DI water with Saponifier cleaning process.
- U17** **Data Retention** The PWB manufacture shall be responsible for retaining micro sections, coupons, and documentation for all items covered under this purchase order for a minimum of 7 years.
- Y06** **SHIP-TO-STOCK** Suppliers and/or products approved and/or certified under Sypris ISO Procedure 8.9.
- V 01** **Workmanship** - The applicable sections of ViaSat workmanship standard 070-QA-044 shall apply. Contact Sypris Electronics buyer for a copy.
- V 02** **Traceability and Data retention** - Material used in this purchase order shall conform to all applicable purchase order requirements and shall be identifiable and traceable to records. The retention period is 7 years. Original or true copies of records related to purchase orders shall be available for review when requested by Sypris Electronics. These records must be retained in a suitable environment to prevent damage or deterioration. In addition to documentation, the PWB manufacturers shall be responsible for retaining micro sections and coupons.
- V 03** **Marking Permanency** - The supplier shall identify each item permanently and legibly in accordance with ANSI/IPC-A-610 and the prescribed method in its detailed document or specification.
- V 04** **Design Control** - No departures from the drawing and/or specification shall be made unless specifically authorized by Sypris Electronics.
- Z50** **SHELF LIFE** – All material with a limited shelf life shall be marked with manufacturing date and shelf life expiration date by manufacturing lot. Materials requiring refrigeration/freezer should NOT be shipped at a time that they would arrive on weekends or holidays.

Q Code Revision History

Deleted Q Codes

(Old Q Codes)

A10 (QG1)	E10 (DC1)	G20 (QF3)	K33	U01 (QA6)	W10 (X3Z)
A11 (QG2)	E12	G21 (Q92)	K34	U02 (Q56)	W11 (Y3Z)
A30 (311)	E14	G22 (Q80)	L02 (QD2)	U03 (QF9)	W20
B01 (QA1)	E16	G23 (MK3)	N01 (QA3)	U20 (QE5)	X01 (QE3)
C05 (QRT)	E20 (LF3)	G30	N02 (QB1)	U30 (QF2)	X02 (QE2)
C10 (QM9)	E30 (LF1)	H01 (Q61)	N03 (QM5)	U31 (QD6)	X03
D01 (QM8)	E40 (LF2)	H02 (QSF)	N04 (QF6)	U32 (QD7)	Y01 (TIS)
D02 (QM1)	E42	H03 (Q97)	N05 (QD9)	U40 (QB2)	Y02 (VSN)
D03 (QA9)	E60	H04 (Q98)	N06 (Q67)	U50 (SMO)	Y03 (COC)
D04 (QC6)	E77	H05 (QF5)	R01 (QA4)	U51 (QPB)	Y04 (PVT)
D05 (QC5)	F01 (QD4)	H06	R02 (Q93)	U60	Z01 (Q64)
D10	F02 (QC8)	K04 (Q20)	R03 (Q94)	V01 (Q81)	Z02
E01 (QB3)	F03 (QD1)	K06 (Q60)	R04 (QF4)	V02 (QC3)	Z10
E02 (QS1)	F04 (QD3)	K07 (QD8)	R05 (Q99)	W01 (QC7)	Z21
E03 (QF7)	G01 (W2V)	K08 (Q89)	R10 (QB6)	W02 (Q96)	Z22
E04 (QE8)	G02 (MK2)	K09 (Q90)	T02 (QA7)	W03 (Q65)	Z23
E05 (Q63)	G03 (QF8)	K10 (Q91)	T03 (Q31)	W04 (QE6)	
E06 (Q66)	G11 (Q25)	K31 (PK8)	T10	W05	

Superceded Q Codes

Q Code in left column replaces Q Code(s) in right column

New Q Code	Old Q Code
A01	A01 (QA5), A02 (Q74), A03 (QD5), A05, A91, A92, A93
A20	A20 (QM7)
CO3	CO1 (QA2), CO2 (QE7), CO3 (QA8), CO4 (QC9), C06 (QE1)
E50	E50, E60
G10	G10 (MK1)
G24	G24
J06	J01 (QB8), J02 (QB7), J03 (QB9), J04 (QTD), J05 (QB5), J06 (Q95)
K01	K01 (Q84)
K02	K02 (Q87)
K03	K03 (Y9Z)
K05	K05 (Q59)
K20	K20 (VB1)
K30	K30 (PK9)
K32	K32 (PK1, PK2, PK3, PK4, PK5, PK6, PK7)
L01	L01 (MSD)
T01	T01 (Q50)
U10	U10 (QE4)
Y06	Y05 (STS), Y06 (SS1), Y07 (SS2)
Z50	Z50

Q-Code Revisions

- 6/6/2000: Added E77
- 8/8/2000: Updated K20
- 4/11/2001: Updated E50, K30, K32, U10; Added U15
- 10/04/2001: Updated E77, K01, K02, K30, and K32
- 3/27/2002: Deleted E77, Added F05
- 12/19/03 Updated K20 (From: IPC/JEDEC J-STD-033 To: IPC/JEDEC J-STD-033A)
- 01/23/04: Removed K20. Updated K30 & K32 (Added Packaging requirement for MOISTURE SENSITIVE parts)
- 06/15/04: Update K03 to include a battery packaging requirement.
- 10/15/04: Added specific flow down requirements as specified for the KG250 contract
- 11/9/04: Added A02 J-STD-001 class 3 flow down requirement.
- 12/15/04: Added CFM code
- 2/11/05: Added U12 for filled micro via's
- 3/22/05 Added U16 requirement per POD ATS-05-002
- 6/2/05 Added U17 requirement per Honeywell data retention requirement
- 9/19/05 Added C06 Certificate of Conformance
- 9/27/05 Added J08 for compliance with AS9102 FAI requirements and added QCode PTM for prototype material.
- 10/20/05 Clarified AS9102 requirements in J08 and added QCode master list
- 1/09/06 Modified U10 to add cross-sectioning requirement to be provided by supplier.
- 3/16/06 Modified A01 to add supplier notification and flow down requirements.
- 8/8/06 Modified Y06 to change ISO procedure 10.6 to 8.9
- 2/12/07 Changed text code 130 (deleted J07 and added J08) and added CPU Tech flow downs. Modified A01 for flow down requirements.
- 12/12/07 Added text to E50 addressing BGA's
- 5/01/08:
 - 1) Rewrote A01 to define the requirements for an Inspection System
 - 2) Created Q-code A03, specific to ISO 9001:2000 standard or Sypris Electronics approved equivalent
 - 3) Created Q-code A04, specific to AS91000 standard or Sypris Electronics approved equivalent
 - 4) Deleted Date Code from G10 (Marking)
 - 5) Deleted U17 and expanded V02 (Traceability and data retention) to incorporate elements of U17 and method of storage.
 - 6) Modified Q-CODE MASTER LIST to add V02 to all Text Numbers, deleted "the date add" column, and added note in regards to Key Suppliers
- 10/16/08:
 - 1) Added statement about nonconforming material to A01, A03 and A04
 - 2) Updated Z50 to prohibit receiving freezer items on a weekend
 - 3) Modified C03 to clarify time
- 04/14/09: Added "using SnPb 63/37 or 60/40" to E50
- 03/23/2010 Updated & Replaced document created by O. Salazar Dated 29 aug 2009 but not placed on FTP site – This is to bring Sypris current for all q-code updates – especially U10.

QCODE MASTER LIST

Text Number	Standard Quality Codes	Keyword Three	Keyword Four
118	A01 C03 E50 F05 G10 K01 K03 V02	AXIAL	T&R or AMMO PACK
119	A01 C03 E50 F05 G10 K02 K03 V02	RADIAL	T&R or AMMO PACK
120	A01 C03 E50 F05 G10 K03 V02	AXIAL/RADIAL	BULK
121	A01 C03 E50 F05G10 K03 K05 V02	DIPS/SOL PKS	TUBES
122	A01 C03 E50 F05 G10 K03 K32 V02	SMD(PASSIVE)	SMD(PASSIVE) T&R
123	A01 C03 E50 F05 G10 K03 K32 V02	SOIC,SOT (T&R)	SOIC,SOT (T&R)
124	A01 C03 E50 F05 G10 K03 K05 V02	SOIC,SOT,SOL,VSO	TUBES
125	A01 C03 E50 F05 G10 K03 K32 V02	PLCC	T&R
126	A01 C03 E50 F05 G10 K03 K30 V02	PLCC,QFP(TRAYS)	PLCC,QFP(TRAYS)
127	A01 C03 E50 F05 G10 K03 V02	SIPS	BULK/TUBES
128	A01 C03 G10 L01 V02	CHEMICALS	
129	A01 C03 G10 V02	HARDWARE	
130	A03 C03 G10 J08 U10 G24 V02	PCB'S	
131	A01 C03 E50 G10 K03 V02	CONN,SOCKETS	CONN,SOCKETS
132	A01 C03 G10 T01 V02	WIRE	
133	A01 C03 G10 V02	MISC	
134	A01 C03 G10 K03 V02	PLASTIC	
135	A01 C03 G10 J07 V02	1 ST ARTICLE REQ'D	HARNESS/CABLES
136	A01 C03 E50 F05 G10 K03 K20 K32 V02	PLCC,MSL, T&R	MOISTURE SENSITIVE
137	A01 C03 E50 F05 G10 K03 K20 K30 V02	PLCC,QFP,MSL-TRAY	MOISTURE SENSITIVE
138	A01 C03 G10 J07 V02	1 ST ARTICLE REQ'D	Simple custom MECH, PLASTIC, ETC
139	A01 C03 G10 L01 Z50 V02	SHELF LIFE MATERIAL	SHELF LIFE
140	A01 C03 G10 J08 V02	AS9102 FAI MECH, ETC	Complex custom Mech parts - AS9102 HONEYWELL
152	A04 C03 G10 J08 U10 U16 U17 V02	AS9102 FAI PWB	HONEYWELL PWBS

Key Suppliers will be evaluated by Supplier Quality Engineering and the q-code for the appropriate quality system will be applied accordingly.